



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS117TC		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA000701052						
<b>Package</b>		PG-TO263-3-2		<b>Weight*</b>		1541.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.361	0.22	0.22	2180	2180
leadframe	non noble metal	iron	7439-89-6	0.304	0.02		197	
	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	copper	7440-50-8	304.026	19.72	19.75	197169	197425
wire	non noble metal	aluminium	7429-90-5	14.841	0.96	0.96	9625	9625
encapsulation	organic material	carbon black	1333-86-4	7.240	0.47		4695	
	inorganic material	antimonytrioxide	1309-64-4	15.138	0.98		9817	
	plastics	brominated resin	-	17.112	1.11		11098	
	plastics	epoxy resin	-	125.051	8.11		81099	
	inorganic material	silicondioxide	60676-86-0	493.622	32.01	42.68	320127	426836
leadfinish	non noble metal	tin	7440-31-5	9.657	0.63	0.63	6263	6263
plating	non noble metal	nickel	7440-02-0	0.228	0.01		148	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	148
glue	plastics	Polyimide	26023-21-2	0.157	0.01	0.01	102	102
solder	noble metal	silver	7440-22-4	0.069	0.00		45	
	non noble metal	tin	7440-31-5	0.055	0.00		36	
	non noble metal	lead	7439-92-1	2.623	0.17	0.17	1701	1782
heatspreader	non noble metal	iron	7439-89-6	0.548	0.04		356	
	inorganic material	phosphorus	7723-14-0	0.165	0.01		107	
	non noble metal	copper	7440-50-8	547.666	35.52	35.57	355175	355639
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com